

Session Program

17-21 Sept 2018



TWEPP 2018 Topical Workshop on Electronics for Particle Physics

Invited

Monday 17 September

16:20

17:05

Invited

Session | **Location:** CAR 0.05/0.06 (aula) | **Convener:** Alessandro Marchioro

16:20-17:05

Technology and challenges for extreme ultraviolet lithography

Speaker

Van Der Zande Wim

Tuesday 18 September

10:45

Invited

Session | **Location:** CAR 0.05/0.06 (aula) | **Convener:** Christine Guo Hu

10:45-11:30

The CMS High Granularity Calorimeter for HL-LHC

Speaker

David Barney

11:30

15:40

Invited

Session | **Location:** CAR 0.05/0.06 (aula) | **Convener:** Marcus Julian French

15:40-16:25

Silicon photonics for next-generation optical interconnects

Speaker

Sebastien Lardenois

16:25

Wednesday 19 September

10:45

Invited

Session | **Location:** CAR 0.05/0.06 (aula) | **Convener:** Ken Wyllie

10:45-11:30

Trends and challenges in monolithic CMOS sensor development for high energy physics

Speaker

Walter Snoeys

11:30

15:45

Invited

Session | **Location:** CAR 0.05/0.06 (aula) | **Convener:** Grzegorz Deptuch

15:45-16:30

It is Time to use Time (for Digital RF Clock Generation and Time-of-Flight)

Speaker

Prof. R. Bogdan Staszewski

16:30

Thursday 20 September

10:45

Invited

Session | **Location:** CAR 0.05/0.06 (aula) | **Convener:** Gregory Michiel Iles

10:45-11:30

Bionic Hearing: the Science and the Experience

Speaker

Shirpsey Ian

11:30

15:45

Invited

Session | **Location:** CAR 0.05/0.06 (aula) | **Convener:** Gui Ping

15:45-16:30

Low noise global shutter pixels and readout circuits for CMOS image sensors

Speaker

Guy Meynants

16:30

Friday 21 September

10:45

11:30

Invited

Session | **Location:** CAR 0.05/0.06 (aula) | **Convener:** Philippe Farthouat

10:45-11:30

Advanced packaging technologies for demanding HEP applications.

Speaker

Stéphane Bellenger